



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

09-Oct-2009

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #16317

TITLE: NCP1595/NCP1595A Transfer and Qualification to Gresham FAB

PROPOSED FIRST SHIP DATE: 03-Mar-2010

AFFECTED CHANGE CATEGORY: Wafer FAB Process

AFFECTED PRODUCT DIVISION: Power Switching (PQ)

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Office or Tim Kaske<Tim.Kaske@onsemi.com> or Paul McDevitt
<paul.mcdevitt@onsemi.com>

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

The purpose of this initial PCN is to notify customers of the qualification and transfer of NCP1595 and NCP1595A devices to ONC25 wafer technology located at ON Semiconductor's wafer fabrication facilities in Gresham, Oregon.

Transfer is being made due to the closure of ON Semiconductor's wafer fabrication facilities at Piestany, Slovakia Republic.


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QUALIFICATION PLAN:

This is to qualify NCP1595 and NCP1595A to ONC25 wafer technology in Gresham, Oregon. No change in packages and assembly sites. The ONC25 is a qualified wafer technology in Gresham. Generic reliability data is available for ONC25 device in 3x3mm DFN-6 package at UTL & SBN assembly factories, which is rated at MSL 1@260°C. With the availability of generic die and package reliability data, NCP1595 and NCP1595A will be qualified to the following requirements:

Test	Condition	Duration	Sample Size	No. of Lot
High Temp. Operating Life Test (HTOL)	JESD22-A108 Ta=125°C	504hrs	80 units/lot	1 wafer lot
Wire Bond Pull Strength Test (WPS)	Mil-883-M2011 Cpk≥1.67	N/A	30 bonds from 5 units	1 lot
Bond Shear Test (BS)	AEC-Q100-001 Cpk≥1.67	N/A	30 bonds from 5 units	1 lot
ESD- Human Body Model (HBM)	JESD22-A114	N/A	3 units/V level	1 wafer lot
ESD- Machine Model (MM)	JESD22-A115	N/A	3 units/V level	1 wafer lot
Latch-up (LU)	JESD78	N/A	6 units	1 wafer lot
Electrical Characterization (ED)	Ta= -40°C, 25°C, 85°C	N/A	30units/lot	3 wafer lots



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AFFECTED DEVICE LIST:

NCP1595MNR2G
NCP1595AMNR2G
NCP1595AMNTWG
NCP1595MNT2G